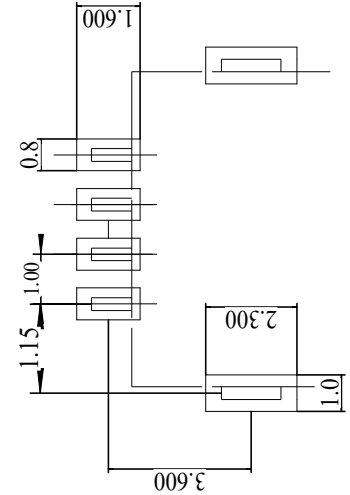
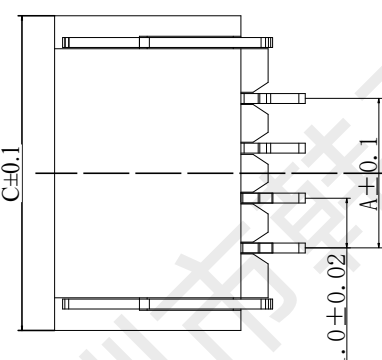
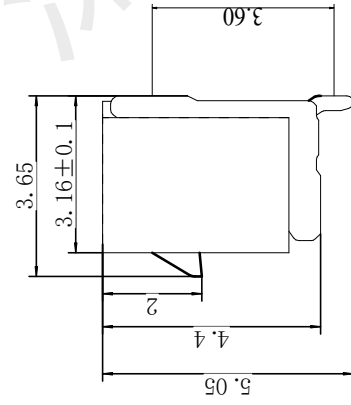
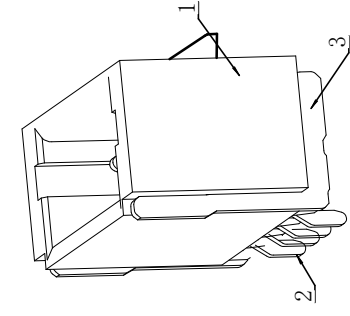
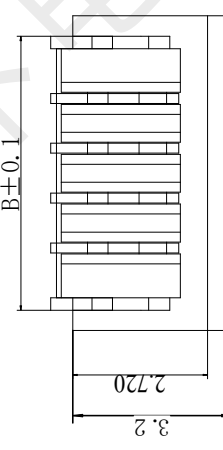


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		板底设计	2020-05-22			

1.0mm	A (mm)	B (mm)	C (mm)
1.0WT-1P	1.00mm	3.50mm	4.30mm
1.0WT-2P	2.00mm	4.50mm	5.30mm
1.0WT-3P	3.00mm	5.50mm	6.30mm
1.0WT-4P	4.00mm	6.50mm	7.30mm
1.0WT-5P	5.00mm	7.50mm	8.30mm
1.0WT-6P	6.00mm	8.50mm	9.30mm
1.0WT-7P	7.00mm	9.50mm	10.30mm
1.0WT-8P	8.00mm	10.50mm	11.30mm
1.0WT-9P	9.00mm	11.50mm	12.30mm
1.0WT-10P	10.00mm	12.50mm	13.30mm
1.0WT-11P	11.00mm	13.50mm	14.30mm
1.0WT-12P	12.00mm	14.50mm	15.30mm
1.0WT-13P	13.00mm	15.50mm	16.30mm
1.0WT-14P	14.00mm	16.50mm	17.30mm
1.0WT-15P	15.00mm	17.50mm	18.30mm
1.0WT-16P	16.00mm	18.50mm	19.30mm
1.0WT-17P	17.00mm	19.50mm	20.30mm
1.0WT-18P	18.00mm	20.50mm	21.30mm
1.0WT-19P	19.00mm	21.50mm	22.30mm
1.0WT-20P	20.00mm	22.50mm	23.30mm



PCB LAYOUT



技术要求:
 1) 材质:见附表;
 2) 电镀:见附表;
 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
 4) 端子表面无氧化、电镀无不良现象。

适应基板厚度: 1.2mm~1.6mm
 温度范围: -25℃~85℃
 额定电压: 125V AC/DC
 额定电流: 1A
 接触电阻: ≤0.02 Ω
 绝缘电阻: ≥100M Ω
 耐压: 500V AC/minute

NO.	NAME	QTY	DESCRIPTION
3	FITTING NAIL	2 PCS	材质:磷青铜,电镀:镀亮锡60u"MIN
2	PIN	n PCS	材质:磷青铜,电镀:镀亮锡60u"MIN
1	Housing	1 PCS	材质:PC (UL94V-0),颜色:本色或黑色

深圳市韩下电子有限公司



DRAW:	黄彬	2020-05-22	TITLE:	针座	DRAW NAME:	HX 1.0mm-10P WTDK
DESIGN:			SERIES:	SHI.0K SERIES	DRAW NO.	
CHECK:	张伟	2020-05-22	P/N:		UNIT:	mm
APPROVED:	罗小春	2020-05-22	REV.	1.00	SCALE	N/A
CUSTOMER DRAWING			SHEET: 1/1			

GENERAL TOLERANCES		
DIM	TOL	DIM DEG
X.		+3.00°
X.X	±0.35	±2.00°
X.XX	±0.25	±1.00°
X.XXX	±0.15	



深圳市韩下电子有限公司

Shenzhen Hanxia Electronic Co., Ltd
Tel: 0755-33819206 Fax: 0755-27597491

承 认 书

SPECIFICATION FOR APPROVAL

客 户 Customer:

产品名称 Project:

针座

规格型号 Part No:

HX 1.0mm-10P WTDK

贵公司承认印 Approval signatures

料 号/Part No.	签 章/Signatures

日期 Date:

拟制/Drawn	黄彬	
审核/Check	张伟	
批准/Approved	罗小春	



1、SCOPE: (适用范围)

1.1 This specification covers production and inspection of Connector.

本规范内容适用于本公司普通系列型条形连接器（针座）产品的生产与检验。

2、USE CONDITION: (使用条件)

2.1 Ambient temperature Range:-25℃~+85℃

环境温度：-25℃~+85℃

2.2 Applicable PC board thickness:1.2~1.6mm

适用 PC 板厚度：1.2~1.6 mm

3、Appearance and Dimension: (外观及尺寸)

3.1 Appearance:Product surface without defect、dirt、crack、and mechanical damang, Contact without rust,plating not oxided and not peeled.

产品表面不应有对制品有害的缺陷、污垢、裂痕及机械损伤；接触件无锈蚀、镀层氧化、脱落等现象。

3.2 Dimension:According to drawings

外形尺寸：依照附图

3.3 Exchangable:Exchangable with same specification products.

互换性：相同规格应能互换

4、Material:

材 料 （以图纸为准）

P/N 零件名称	Type 类 型	Material 材 料	Finish 表面处理	Expiain 说 明
Terminal 端子	Contact 插 簧	Phosphor bronze 锡青磷铜 厚 0.15mm	Tin Plating:3~4 μ m 镀锡：3~4 μ m	RoHS Comp liant
Housing 孔 座	Plastic 塑 壳	Nylon66 UL94V-0	Color:White 颜色：白色	
OpeningWafer 开口针座	Contact 插 针	Phosphor bronze 锡青磷铜 厚 0.30mm	Tin Plating:3~4 μ m 镀锡：3~4 μ m	
	Plastic 塑 壳	Nylon46 UL94V-0	Color: Beige 颜色：米色	
Lips Wafer 闭口针座	Contact 插 针	Phosphor bronze 锡青磷铜 厚 0.30mm	Gold Plating:3~4 μ " m 镀金：3~4 μ " m	
	Plastic 塑 壳	PBT UL94V-0	Color: White 颜色：白色	
Tiepian Wafer 卧贴针座 立贴针座	Contact 插 针	Phosphor bronze 锡青磷铜 厚 0.30mm	Tin Plating:3~4 μ m 镀锡：3~4 μ m	
	Solder tabs 焊护耳	Phosphor bronze 锡青磷铜 厚 0.25mm	Tin Plating:3~4 μ m 镀锡：3~4 μ m	
	Plastic 塑 壳	Nylon46 UL94V-0	Color: Beige 颜色：米色	



5、Electrical Performance:

电气性能

NO. 序号	Item 项目	Requirement 技术要求
5.1	Voltage Rated 额定电压	125V AC DC
5.2	Current Rated 额定电流	1A AC DC
5.3	Contact Resistance 接触电阻	$\leq 20 \text{ m}\Omega$
5.4	Insulation Resistance 绝缘电阻	$\geq 100 \text{ M}\Omega$
5.5	Dielectric Strength 耐压	$\geq 500 \text{ V AC/minute}$

6、Mechanical Performance:

机械性能

NO. 序号	Item 项目	Requirement 技术要求
6.1	Male contact Retention force PIN 针固定力	$\geq 10 \text{ N}$ per pin
6.2	Female contact Retention force 端子固定力	$\geq 10 \text{ N}$ per pin
6.3	Plug-in force 插入力	$\leq 3 \text{ N}$ per pin
6.4	Plug-out force 拔出力	$\geq 0.5 \text{ N}$ per pin

7、Endurance Characteristics:

环境性能

NO. 序号	Item 项目	Requirement 技术要求
7.1	Soldering rest 可焊性	Time: $2.5 \pm 0.5 \text{ S}$ 时间: $2.5 \pm 0.5 \text{ S}$ Temperature: $260 \pm 5^\circ \text{C}$ 温度: $260 \pm 5^\circ \text{C}$ Area of Soldering: $\geq 95\%$ 焊锡面积: $\geq 95\%$
7.2	Resistance to soldering Heat 耐焊接热	Time: $5 \pm 1 \text{ S}$ 时间: $5 \pm 1 \text{ S}$ Temperature: $260 \pm 5^\circ \text{C}$ 温度: $260 \pm 5^\circ \text{C}$ Appearance: NO Damage 外观: 无损坏

7.3	<p>Heat test 耐热性</p>	<p>Time:96h 时间: 96 小时 Temperature:+85±3℃ 温度: +85±3℃ Appearance:NO Damage 外观: 无损坏 Contact resistance: ≤20 mΩ 接触电阻: ≤20 mΩ</p>
7.4	<p>Cold test 耐冷性</p>	<p>Time:48h 时间: 48 小时 Temperature:-25±3℃ 温度: -25±3℃ Appearance:NO Damage 外观: 无损坏 Contact resistance:≤20 mΩ 接触电阻: ≤20 mΩ</p>
7.5	<p>Temperature Cycling 温度循环</p>	<p>Low temperature:-25±3℃ 低温: -25±3℃ High temperature:85±3℃ 高温: 85±3℃ For 5 cycles.test after keeping in Normal Condition for 30 min. 5 次循环后, 放置在正常环境中 30 分钟, 在进行测试 Appearance: NO Damage 外观: 无损坏 Contact resistance: ≤20 mΩ 接触电阻: ≤20mΩ</p>
7.6	<p>Invariab lenes humidity 恒定湿热</p>	<p>Temperature:60±2℃ 温度: 60±2℃ Relative humidity:90%-96% RH 相对湿度: 90%-96% RH Tim:96h 时间: 96 小时 Appearance:NO Damage 外观: 无损坏 Contact resistance: ≤20 mΩ 接触电阻: ≤20 mΩ Insulation Resistance: ≥100MΩ 绝缘电阻: ≥100 MΩ</p>
7.7	<p>Salt Spray 盐雾试验</p>	<p>Salt concentration: 5±1% 浓度: 5±1% Temperature:35±2℃ 温度: 35±2℃ Tim:16±2h 时间: 16±2 小时 After salt is removed by running wafer and A drop is removed ,it is measured. 把试验样品从试验箱顶悬挂下来, 采用浓度 (5±1) %的氯化钠溶液, 连续雾化 16 小时, 试验后用流动的蒸馏水 轻轻洗去表面沉积物, 在常温常驻湿条件下恢复 1-2 小时, 外观无损伤 Appearance:NO Damage 外观: 无损坏 Contact resistance: ≤20 mΩ 接触电阻: ≤20 mΩ</p>